



PR/158331 | Packaging Engineer

Job Information

Recruiter

JAC Recruitment Malaysia

Job ID

1509164

Industry

Other (Manufacturing)

Job Type

Permanent Full-time

Location

Malaysia

Salary

Negotiable, based on experience

Refreshed

December 11th, 2024 15:31

General Requirements

Minimum Experience Level

Over 3 years

Career Level

Mid Career

Minimum English Level

Business Level

Minimum Japanese Level

Business Level

Minimum Education Level

Associate Degree/Diploma

Visa Status

No permission to work in Japan required

Job Description

A US based equipment manufacturing company is looking for Packaging Engineer to responsible for designing, developing, and testing packaging solutions to ensure products are safely and efficiently packaged.

Job Responsibilities

- Collaborates with staff from manufacturing, Quality, Design, and shipping departments to optimize package design.
- Oversees the design of the finished product packaging & crating. Maintains knowledge base of customer specific crating or marking requirements
- Oversees the design of raw material to meet the technical requirements: Cleanroom compatibility etc...
- Tests packaging systems and components for new and existing products.
- Uses 3D modeling software to extract key design and weight requirements for packaging design.

- Researches and introduces prototype packaging suitable for Semiconductor capital equipment and respective components/ assemblies.
- Drafts specifications for new packing materials that will adequately protect finished products.
- Technical Interface with packaging suppliers (USA and Asia) who provide packaging material to the company and its suppliers.
- Working alongside new product development teams to identify specialty packaging needs.
- Maintains, updates and releases Cleanroom packaging and Crating specifications
- Point of contact for the company suppliers of packaging or require packaging designs be approved.

Job Requirement

- Extensive knowledge of packaging material and design as it applies to Cleanroom/ semiconductor equipment
- Bachelor's degree in Materials Engineering or related field required.
- At least 5 years of experience in package design preferred
- Capable in using Solidworks, Autocad or Creo

Company Description